

EiceDRIVER™

High voltage gate driver IC

6ED family - 2nd generation

3 phase 200 V and 600 V gate drive IC

6EDL04I06PT

6EDL04I06NT

6EDL04N06PT

6EDL04N02PR

EiceDRIVER™

datasheet

<Revision 2.5>, 15.04.2015

Edition 15.04.2015

**Published by
Infineon Technologies AG
81726 Munich, Germany**

**© 2015 Infineon Technologies AG
All Rights Reserved.**

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Revision History

Page or Item	Subjects (major changes since previous revision)
<Revision 2.5>, 15.04.2015	
all	Revised wording for test temperature
p. 22	Inserted Figure 18 ITRIP input timing
p. 20	Revised Figure 9

Trademarks of Infineon Technologies AG

AURIX™, BlueMoon™, C166™, CanPAK™, CIPOS™, CIPURSE™, COMNEON™, EconoPACK™, CoolMOS™, CoolSET™, CORECONTROL™, CROSSAVE™, DAVE™, EasyPIM™, EconoBRIDGE™, EconoDUAL™, EconoPIM™, EiceDRIVER™, eupec™, FCOS™, HITFET™, HybridPACK™, I²RF™, ISOFACE™, IsoPACK™, MIPAQ™, ModSTACK™, my-d™, NovalithIC™, OmniTune™, OptiMOS™, ORIGA™, PRIMARION™, PrimePACK™, PrimeSTACK™, PRO-SIL™, PROFET™, RASIC™, ReverSave™, SatRIC™, SIEGET™, SINDRION™, SIPMOS™, SMARTi™, SmartLEWIS™, SOLID FLASH™, TEMPFET™, thinQ!™, TRENCHSTOP™, TriCore™, X-GOLD™, X-PMU™, XMM™, XPOSYS™.

Other Trademarks

Advance Design System™ (ADS) of Agilent Technologies, AMBA™, ARM™, MULTI-ICE™, KEIL™, PRIMECELL™, REALVIEW™, THUMB™, μVision™ of ARM Limited, UK. AUTOSAR™ is licensed by AUTOSAR development partnership. Bluetooth™ of Bluetooth SIG Inc. CAT-iq™ of DECT Forum. COLOSSUS™, FirstGPS™ of Trimble Navigation Ltd. EMV™ of EMVCo, LLC (Visa Holdings Inc.). EPCOS™ of Epcos AG. FLEXGO™ of Microsoft Corporation. FlexRay™ is licensed by FlexRay Consortium. HYPERTERMINAL™ of Hilgraeve Incorporated. IEC™ of Commission Electrotechnique Internationale. IrDA™ of Infrared Data Association Corporation. ISO™ of INTERNATIONAL ORGANIZATION FOR STANDARDIZATION. MATLAB™ of MathWorks, Inc. MAXIM™ of Maxim Integrated Products, Inc. MICROTEC™, NUCLEUS™ of Mentor Graphics Corporation. Mifare™ of NXP. MIPI™ of MIPI Alliance, Inc. MIPS™ of MIPS Technologies, Inc., USA. muRata™ of MURATA MANUFACTURING CO., MICROWAVE OFFICE™ (MWO) of Applied Wave Research Inc., OmniVision™ of OmniVision Technologies, Inc. Openwave™ Openwave Systems Inc. RED HAT™ Red Hat, Inc. RFMD™ RF Micro Devices, Inc. SIRIUS™ of Sirius Satellite Radio Inc. SOLARIS™ of Sun Microsystems, Inc. SPANSION™ of Spansion LLC Ltd. Symbian™ of Symbian Software Limited. TAIYO YUDEN™ of Taiyo Yuden Co. TEAKLITE™ of CEVA, Inc. TEKTRONIX™ of Tektronix Inc. TOKO™ of TOKO KABUSHIKI KAISHA TA. UNIX™ of X/Open Company Limited. VERILOG™, PALLADIUM™ of Cadence Design Systems, Inc. VLYNQ™ of Texas Instruments Incorporated. VXWORKS™, WIND RIVER™ of WIND RIVER SYSTEMS, INC. ZETEX™ of Diodes Zetex Limited.

Last Trademarks Update 2010-10-26

Table of Contents

1	Overview	7
2	Blockdiagram.....	9
3	Pin configuration, description, and functionality	11
3.1	Low Side and High Side Control Pins (Pin 2, 3, 4, 5, 6, 7)	11
3.2	EN (Gate Driver Enable, Pin 10)	12
3.3	/FAULT (Fault Feedback, Pin 8)	12
3.4	ITRIP and RCIN (Over-Current Detection Function, Pin 9, 11)	13
3.5	VCC, VSS and COM (Low Side Supply, Pin 1, 12,13)	13
3.6	VB1,2,3 and VS1,2,3 (High Side Supplies, Pin 18, 20, 22, 24, 26, 28)	13
3.7	LO1,2,3 and HO1,2,3 (Low and High Side Outputs, Pin 14, 15, 16, 19, 23, 27)	13
4	Electrical Parameters.....	14
4.1	Absolute Maximum Ratings	14
4.2	Required operation conditions	15
4.3	Operating Range	15
4.4	Static logic function table	16
4.5	Static parameters	16
4.6	Dynamic parameters	19
5	Timing diagrams.....	20
6	Package.....	23
6.1	PG-DSO-28	23
6.2	PG-TSSOP-28.....	24

List of Figures

Figure 1	Typical Application	8
Figure 2	Block diagram for 6EDL04I06NT	9
Figure 3	Block Diagram for 6EDL04I06PT, and 6EDL04N06PT / 6EDL04N02PR.....	10
Figure 4	Pin Configuration of 6ED family (signals HIN1,2,3 and LIN1,2,3 according to Table 1).....	11
Figure 5	Input pin structure for negative logic (left) and positive logic (right).....	12
Figure 6	Input filter timing diagram for negative logic (left) and positive logic (right)	12
Figure 7	EN pin structures.....	12
Figure 8	/FAULT pin structures	13
Figure 9	Timing of short pulse suppression (6EDL04I06NT)	20
Figure 10	Timing of short pulse suppression (6EDL04I06PT, 6EDL04N06PT, 6EDL04N02PR)	20
Figure 11	Timing of of internal deadtime (input logic according to Table 1)	20
Figure 12	Enable delay time definition	21
Figure 13	Input to output propagation delay times and switching times definition (6EDL04I06NT)	21
Figure 14	Input to output propagation delay times and switching times definition (6EDL04I06PT, 6EDL04N06PT, 6EDL04N02PR)	21
Figure 15	Operating areas (6EDL04I06NT, 6EDL04I06PT)	21
Figure 16	Operating Areas (6EDL04N06PT, 6EDL04N02PR).....	22
Figure 17	ITRIP-Timing	22
Figure 18	Package drawing.....	23
Figure 19	PCB reference layout	23
Figure 20	Package drawing.....	24
Figure 21	PCB reference layout (according to JEDEC 1s0P) left: Reference layout right: detail of footprint	24

List of Tables

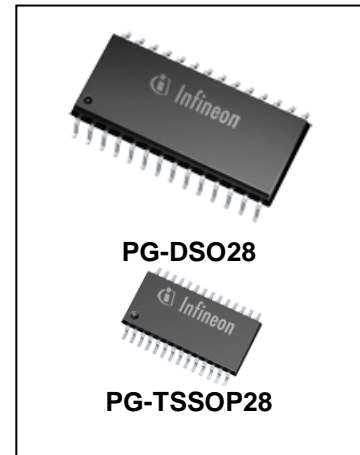
Table 1	Members of 6ED family – 2 nd generation	7
Table 2	Pin Description	11
Table 3	Abs. maximum ratings.....	14
Table 4	Required Operation Conditions	15
Table 5	Operating range	15
Table 6	Static parameters	16
Table 7	Dynamic parameters	19
Table 8	Data of reference layout.....	24

EiceDRIVER™
3 phase 200 V and 600 V gate drive IC

1 Overview

Main features

- Thin-film-SOI-technology
- Maximum blocking voltage +600V
- Separate control circuits for all six drivers
- CMOS and LSTTL compatible input (negative logic)
- Signal interlocking of every phase to prevent cross-conduction
- Detection of over current and under voltage supply
- externally programmable delay for fault clear after over current detection



Product highlights

- Insensitivity of the bridge output to negative transient voltages up to -50V given by SOI-technology
- Ultra fast bootstrap diodes
- 'shut down' of all switches during error conditions

Typical applications

- Home appliances
- Fans, pumps
- General purpose drives

Product family

Table 1 Members of 6ED family – 2nd generation

Sales Name	high side control input HIN1,2,3 and LIN1,2,3	typ. UVLO- Thresholds	Bootstrap diode	Package
6EDL04I06NT	negative logic	11.7 V / 9.8 V	Yes	DSO28
6EDL04I06PT	positive logic	11.7 V / 9.8 V	Yes	DSO28
6EDL04N06PT / 6EDL04N02PR	positive logic	9 V / 8.1 V	Yes	DSO28 / TSSOP28

Description

The device 6ED family – 2nd generation is a full bridge driver to control power devices like MOS-transistors or IGBTs in 3-phase systems with a maximum blocking voltage of +600 V. Based on the used SOI-technology there is an excellent ruggedness on transient voltages. No parasitic thyristor structures are present in the device. Hence, no parasitic latch-up may occur at all temperatures and voltage conditions.

The six independent drivers are controlled at the low-side using CMOS resp. LSTTL compatible signals, down to 3.3 V logic. The device includes an under-voltage detection unit with hysteresis characteristic and an over-current detection. The over-current level is adjusted by choosing the resistor value and the threshold level at pin ITRIP. Both error conditions (under-voltage and over-current) lead to a definite shut down off all six switches. An error signal is provided at the FAULT open drain output pin. The blocking time after over-current can be adjusted with an RC-network at pin RCIN. The input RCIN owns an internal current source of 2.8 µA. Therefore, the resistor R_{RCIN} is optional. The typical output current can be given with 165 mA for pull-up and 375 mA for pull down. Because of system safety reasons a 310 ns interlocking time has been realised. The function of input EN can optionally be extended with an over-temperature detection, using an external NTC-resistor (see Fig.1). The

monolithic integrated bootstrap diode structures between pins VCC and VBx can be used for power supply of the high side.

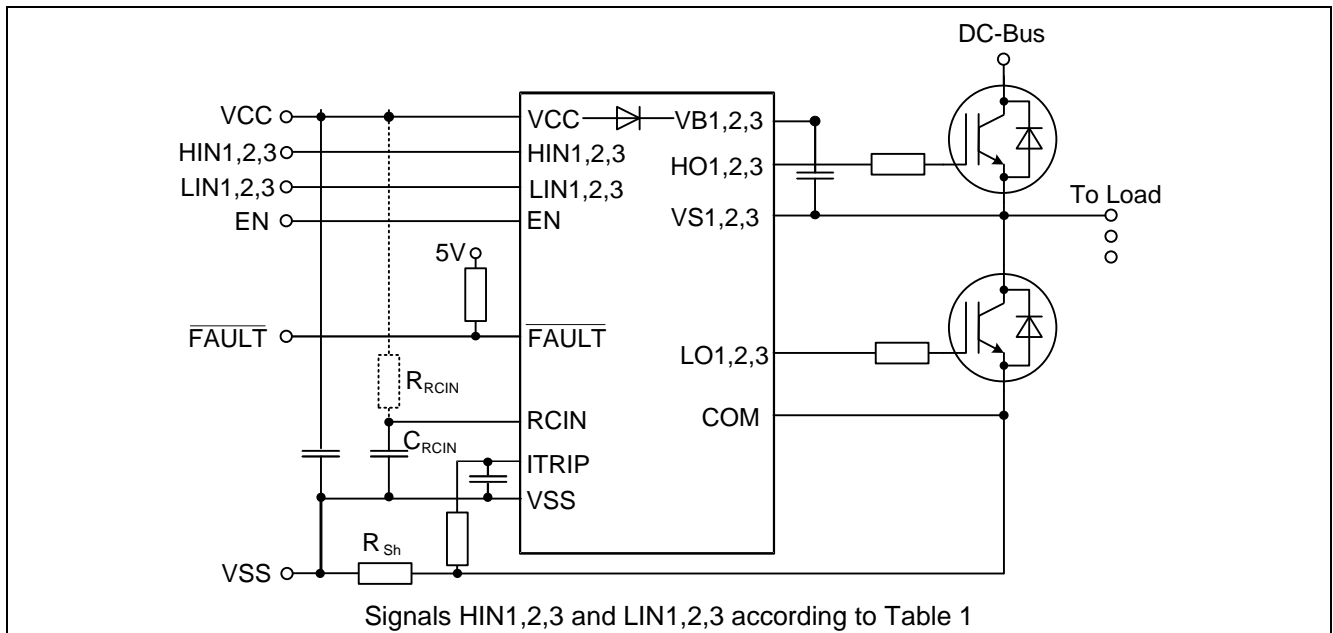


Figure 1 Typical Application

2 Blockdiagram

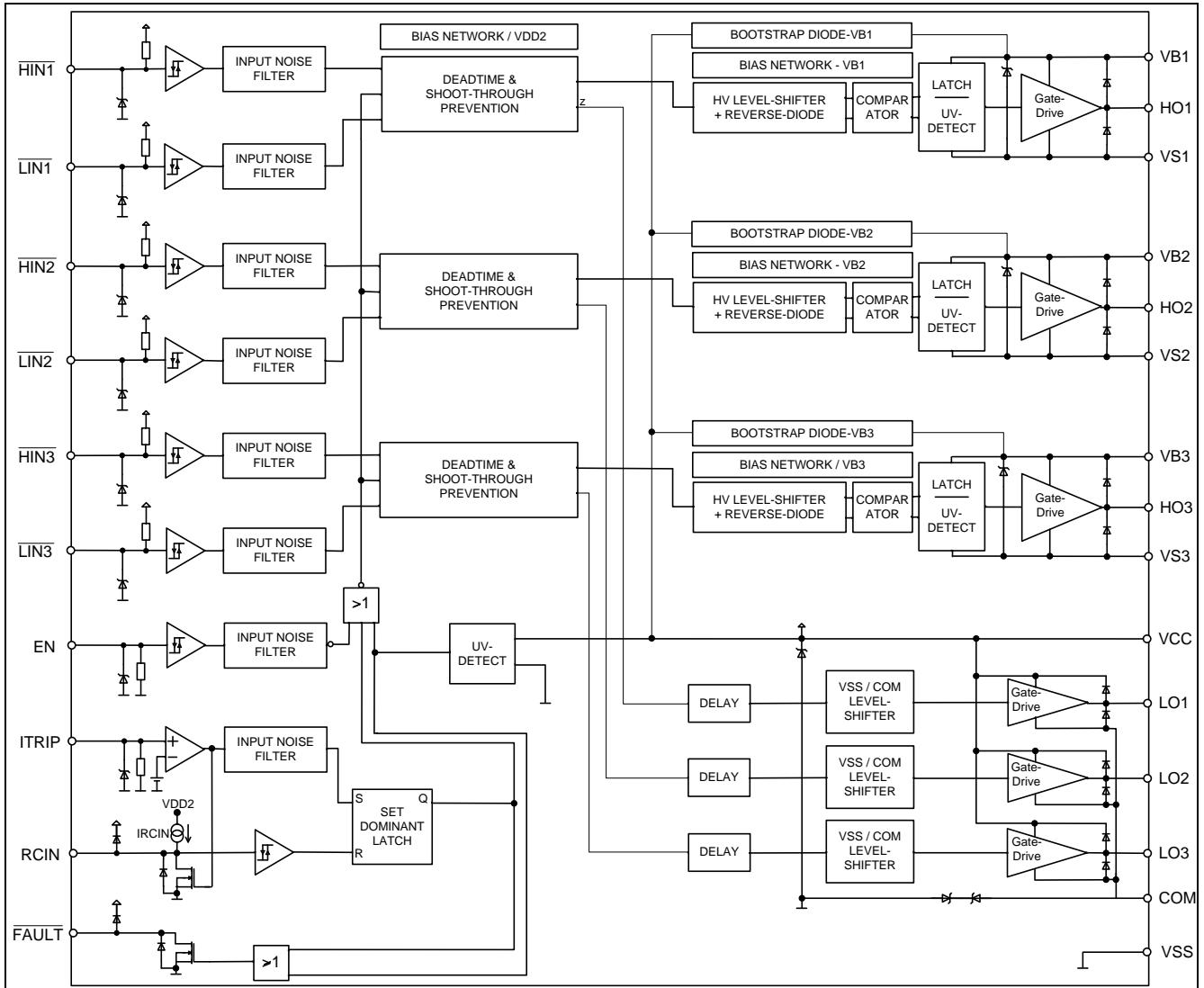


Figure 2 Block diagram for 6EDL04I06NT

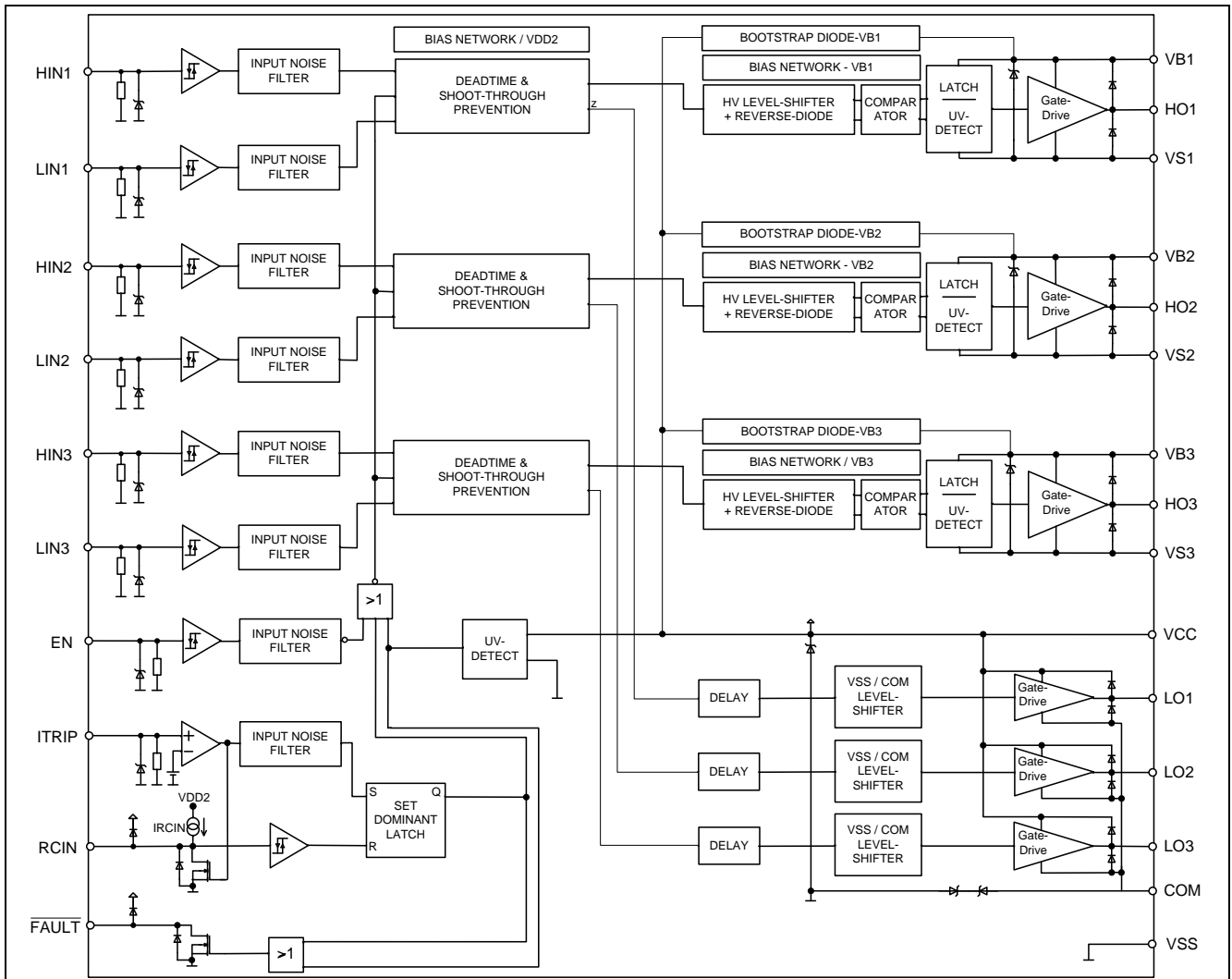


Figure 3 Block Diagram for 6EDL04I06PT, and 6EDL04N06PT / 6EDL04N02PR

3 Pin configuration, description, and functionality

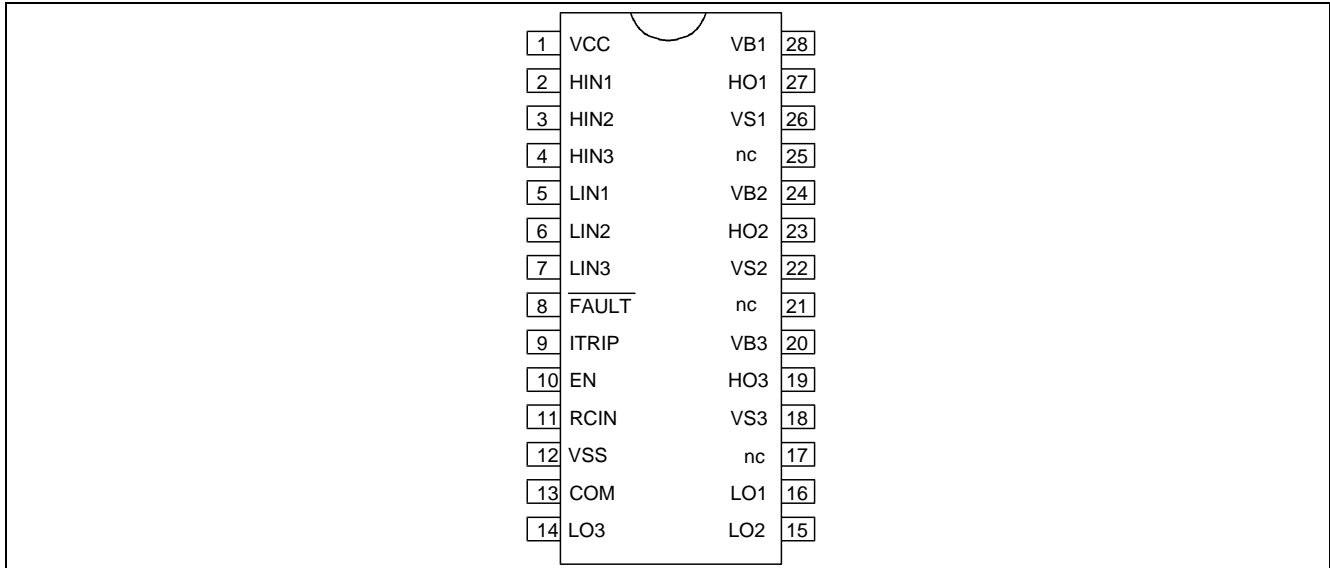


Figure 4 Pin Configuration of 6ED family (signals HIN1,2,3 and LIN1,2,3 according to Table 1)

Table 2 xPin Description

Symbol	Description
VCC	Low side power supply
VSS	Logic ground
HIN1,2,3	High side logic input (positive or negative logic according to Table 1)
LIN1,2,3	Low side logic input (positive or negative logic according to Table 1)
/FAULT	Indicates over-current and under-voltage (negative logic, open-drain output)
EN	Enable I/O functionality (positive logic)
ITRIP	Analog input for over-current shut down, activates FAULT and RCIN to VSS
RCIN	External RC-network to define FAULT clear delay after FAULT-Signal (T_{FLTCLR})
COM	Low side gate driver reference
VB1,2,3	High side positive power supply
HO1,2,3	High side gate driver output
VS1,2,3	High side negative power supply
LO1,2,3	Low side gate driver output
nc	Not connected

3.1 Low Side and High Side Control Pins (Pin 2, 3, 4, 5, 6, 7)

The Schmitt trigger input threshold of them are such to guarantee LSTTL and CMOS compatibility down to 3.3 V controller outputs. Input Schmitt trigger and noise filter provide beneficial noise rejection to short input pulses according to Figure 5 and Figure 6.

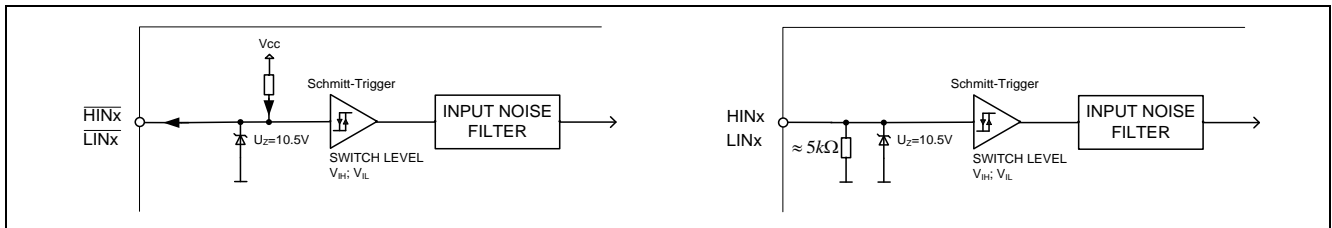


Figure 5 Input pin structure for negative logic (left) and positive logic (right)

An internal pull-up of about 75 kΩ (negative logic) pre-biases the input during supply start-up and a ESD zener clamp is provided for pin protection purposes. The zener diodes are therefore designed for single pulse stress only and not for continuous voltage stress over 10V. For versions with positive, a 5 kΩ pull-down resistor is used for this function.

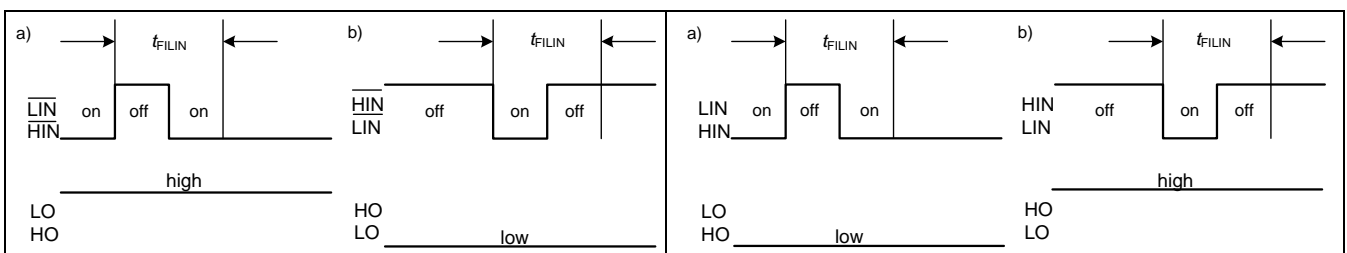


Figure 6 Input filter timing diagram for negative logic (left) and positive logic (right)

It is anyway recommended for proper work of the driver not to provide input pulse-width lower than 1 μs.

The 6ED family – 2nd generation provides additionally a shoot through prevention capability which avoids the simultaneous on-state of two channels of the same leg (i.e. HO1 and LO1, HO2 and LO2, HO3 and LO3). When two inputs of a same leg are activated, only one leg output is activated, so that the leg is kept steadily in a safe state. Please refer to the application note [AN-Gatedrive-6ED2-1](#) for a detailed description.

A minimum dead time insertion of typ. 310 ns is also provided, in order to reduce cross-conduction of the external power switches.

3.2 EN (Gate Driver Enable, Pin 10)

The signal applied to pin EN controls directly the output stages. All outputs are set to LOW, if EN is at LOW logic level. The internal structure of the pin is given in Figure 7. The switching levels of the Schmitt-Trigger are here $V_{EN,TH+} = 2.1$ V and $V_{EN,TH-} = 1.3$ V. The typical propagation delay time is $t_{EN} = 780$ ns. There is an internal pull down resistor (75 kΩ), which keeps the gate outputs off in case of broken PCB connection.

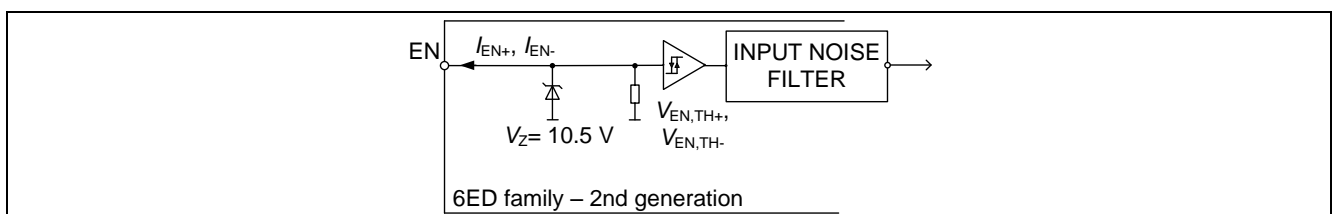


Figure 7 EN pin structures

3.3 /FAULT (Fault Feedback, Pin 8)

/Fault pin is an active low open-drain output indicating the status of the gate driver (see Figure 8). The pin is active (i.e. forces LOW voltage level) when one of the following conditions occur:

- Under-voltage condition of VCC supply: In this case the fault condition is released as soon as the supply voltage condition returns in the normal operation range (please refer to VCC pin description for more details).
- Over-current detection (ITRIP): The fault condition is latched until current trip condition is finished and RCIN input is released (please refer to ITRIP pin).

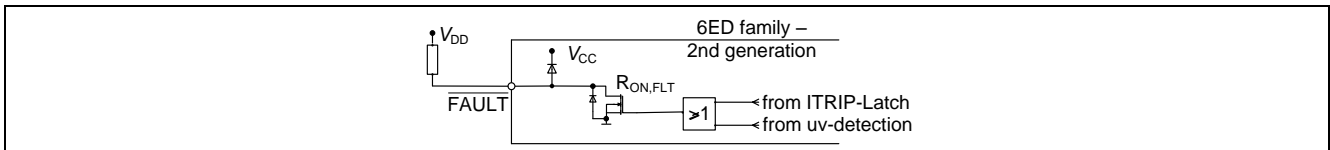


Figure 8 /FAULT pin structures

3.4 ITRIP and RCIN (Over-Current Detection Function, Pin 9, 11)

The 6ED family – 2nd generation provides an over-current detection function by connecting the ITRIP input with the motor current feedback. The ITRIP comparator threshold (typ 0.44 V) is referenced to VSS ground. A input noise filter (typ. $t_{TRIPMIN} = 230$ ns) prevents the driver to detect false over-current events.

Over-current detection generates a hard shut down of all outputs of the gate driver and provides a latched fault feedback at /FAULT pin. RCIN input/output pin is used to determine the reset time of the fault condition. As soon as ITRIP threshold is exceeded the external capacitor connected to RCIN is fully discharged. The capacitor is then recharged by the RCIN current generator when the over-current condition is finished. As soon as RCIN voltage exceeds the rising threshold of typ $V_{RCIN,TH} = 5.2$ V, the fault condition releases and the driver returns operational following the control input pins according to section 3.1. Please refer to [AN-Gatedrive-6ED2-1](#) for details on setting RCIN time constant.

3.5 VCC, VSS and COM (Low Side Supply, Pin 1, 12,13)

VCC is the low side supply and it provides power both to input logic and to low side output power stage. Input logic is referenced to VSS ground as well as the under-voltage detection circuit. Output power stage is referenced to COM ground. COM ground is floating respect to VSS ground with a maximum range of operation of +/-5.7 V. A back-to-back zener structure protects grounds from noise spikes.

The under-voltage circuit enables the device to operate at power on when a typical supply voltage higher than V_{CCUV+} is present.

The IC shuts down all the gate drivers power outputs, when the VCC supply voltage is below $V_{CCUV-} = 9.8$ V respectively 8.1 V. This prevents the external power switches from critically low gate voltage levels during on-state and therefore from excessive power dissipation.

3.6 VB1,2,3 and VS1,2,3 (High Side Supplies, Pin 18, 20, 22, 24, 26, 28)

VB to VS is the high side supply voltage. The high side circuit can float with respect to VSS following the external high side power device emitter/source voltage. Due to the low power consumption, the floating driver stage can be supplied by bootstrap topology connected to VCC.

The device operating area as a function of the supply voltage is given in Figure 15 and Figure 16. Details on bootstrap supply section and transient immunity can be found in application note [AN-Gatedrive-6ED2-1](#).

3.7 LO1,2,3 and HO1,2,3 (Low and High Side Outputs, Pin 14, 15, 16, 19, 23, 27)

Low side and high side power outputs are specifically designed for pulse operation such as gate drive of IGBT and MOSFET devices. Low side outputs (i.e. LO1,2,3) are state triggered by the respective inputs, while high side outputs (i.e. HO1,2,3) are edge triggered by the respective inputs. In particular, after an under voltage condition of the VBS supply, a new turn-on signal (edge) is necessary to activate the respective high side output, while after a under voltage condition of the VCC supply, the low side outputs switch to the state of their respective inputs.

4 Electrical Parameters

4.1 Absolute Maximum Ratings

All voltages are absolute voltages referenced to V_{SS} -potential unless otherwise specified. All parameters are valid for $T_a=25\text{ }^\circ\text{C}$.

Table 3 Abs. maximum ratings

Parameter	Symbol	Min.	Max.	Unit
High side offset voltage(Note 1)	V_S	$V_{CC}-V_{BS}-6$	600 180	V
High side offset voltage ($t_p<500\text{ns}$, Note 1)		$V_{CC}-V_{BS}-50$	–	
High side offset voltage(Note 1)	V_B	$V_{CC}-6$	620 200	
High side offset voltage ($t_p<500\text{ns}$, Note 1)		$V_{CC}-50$	–	
High side floating supply voltage (V_B vs. V_S) (internally clamped)	V_{BS}	-1	20	
High side output voltage (V_{HO} vs. V_S)	V_{HO}	-0.5	$V_B + 0.5$	
Low side supply voltage (internally clamped)	V_{CC}	-1	20	
Low side supply voltage (V_{CC} vs. V_{COM})	V_{CCOM}	-0.5	25	
Gate driver ground	V_{COM}	-5.7	5.7	
Low side output voltage (V_{LO} vs. V_{COM})	V_{LO}	-0.5	$V_{CCOM} + 0.5$	
Input voltage LIN,HIN,EN,ITRIP	V_{IN}	-1	10	
FAULT output voltage	V_{FLT}	-0.5	$V_{CC} + 0.5$	
RCIN output voltage	V_{RCIN}	-0.5	$V_{CC} + 0.5$	
Power dissipation (to package) Note 2	P_D	–	1.3	W
		–	0.6	
Thermal resistance (junction to ambient, see section 6)	$R_{th(j-a)}$	–	75	K/W
		–	165	
Junction temperature	T_J	–	125	$^\circ\text{C}$
Storage temperature	T_S	- 40	150	
offset voltage slew rate (Note 3)	dV_S/dt		50	V/ns

Note :The minimum value for ESD immunity is 1.0kV (Human Body Model). ESD immunity inside pins connected to the low side (V_{CC} , $HINx$, $LINx$, $FAULT$, EN , $RCIN$, $ITRIP$, V_{SS} , COM , LOx) and pins connected inside each high side itself (V_{Bx} , HOx , VSx) is guaranteed up to 1.5kV (Human Body Model).

Note 1 : In case $V_{CC} > V_B$ there is an additional power dissipation in the internal bootstrap diode between pins V_{CC} and V_{Bx} . Insensitivity of bridge output to negative transient voltage up to -50V is not subject to production test – verified by design / characterization.

Note 2: Consistent power dissipation of all outputs. All parameters inside operating range.

Note 3: Not subject of production test, verified by characterisation

4.2 Required operation conditions

All voltages are absolute voltages referenced to V_{SS} -potential unless otherwise specified. All parameters are valid for $T_a=25\text{ °C}$.

Table 4 Required Operation Conditions

Parameter		Symbol	Min.	Max.	Unit
High side offset voltage (Note 1)	DSO28 TSSOP28	V_B	7	620 200	V
Low side supply voltage (V_{CC} vs. V_{COM})	DSO28 TSSOP28	V_{CCOM}	10	25	

4.3 Operating Range

All voltages are absolute voltages referenced to V_{SS} -potential unless otherwise specified. All parameters are valid for $T_a=25\text{ °C}$.

Table 5 Operating range

Parameter		Symbol	Min.	Max.	Unit
High side floating supply offset voltage		V_S	$V_{CC} - V_{BS} - 1$	500	V
High side floating supply offset voltage (V_B vs. V_{CC} , statically)		V_{BCC}	-1.0	500	
High side floating supply voltage (V_B vs. V_S , Note 1)	6EDL04I06NT 6EDL04I06PT	V_{BS}	13	17.5	
	6EDL04N06PT 6EDL04N02PR		10	17.5	
High side output voltage (V_{HO} vs. V_S)		V_{HO}	10	V_{BS}	
Low side output voltage (V_{LO} vs. V_{COM})		V_{LO}	0	V_{CC}	
Low side supply voltage	6EDL04I06NT 6EDL04I06PT	V_{CC}	13	17.5	
	6EDL04N06PT 6EDL04N02PR		10	17.5	
Low side ground voltage		V_{COM}	-2.5	2.5	
Logic input voltages LIN,HIN,EN,ITRIP (Note 2)		V_{IN}	0	5	
FAULT output voltage		V_{FLT}	0	V_{CC}	
RCIN input voltage		V_{RCIN}	0	V_{CC}	
Pulse width for ON or OFF (Note 3)		t_{IN}	1	–	μs
Ambient temperature		T_a	-40	95	°C

Note 1 : Logic operational for V_B (V_B vs. V_S) > 7,0V

Note 2 : All input pins (HINx, LINx) and EN, ITRIP pin are internally clamped (see abs. maximum ratings)

Note 3 : In case of input pulse width at LINx and HINx below 1μ the input pulse may not be transmitted properly

4.4 Static logic function table

VCC	VBS	RCIN	ITRIP	ENABLE	FAULT	LO1,2,3	HO1,2,3
<V _{CCUV-}	X	X	X	X	0	0	0
15V	<V _{BSUV-}	X	0	3.3 V	High imp	LIN1,2,3*	0
15V	15V	<3.2 V ↓	0	3.3 V	0	0	0
15V	15V	X	> V _{IT,TH+}	3.3 V	0	0	0
15V	15V	> V _{RCIN,TH}	0	3.3 V	High imp	LIN1,2,3*	HIN1,2,3*
15V	15V	> V _{RCIN,TH}	0	0	High imp	0	0

* according to Table 1

4.5 Static parameters

V_{CC} = V_{BS} = 15V unless otherwise specified. All parameters are valid for T_a=25 °C.

Table 6 Static parameters

Parameter	Symbol	Values			Unit	Test condition
		Min.	Typ.	Max.		
High level input voltage	V _{IH}	1.7	2.1	2.4	V	
Low level input voltage	V _{IL}	0.7	0.9	1.1		
EN positive going threshold	V _{EN,TH+}	1.9	2.1	2.3		
EN negative going threshold	V _{EN,TH-}	1.1	1.3	1.5		
ITRIP positive going threshold	V _{IT,TH+}	380	445	510	mV	
ITRIP input hysteresis	V _{IT,HYS}	45	70			
RCIN positive going threshold	V _{RCIN,TH}	-	5.2	6.4	V	
RCIN input hysteresis	V _{RCIN,HYS}	-	2.0	-		
Input clamp voltage (HIN and LIN acc. Table 1, EN, ITRIP)	V _{IN,CLMAP}	9	10.3	12		I _{IN} = 4mA
Input clamp voltage at high impedance (/HIN, /LIN negative logic only)	V _{IN,FLOAT}	-	5.3	5.8		controller output pin floating
High level output voltage	LO1,2,3 HO1,2,3	V _{OH}	-	V _{CC} -0.7	V _{CC} -1.4	I _O = 20mA
			-	V _B -0.7	V _B -1.4	
Low level output voltage	LO1,2,3 HO1,2,3	V _{OL}	-	V _{COM+} 0.2	V _{COM+} 0.6	I _O = -20mA
			-	V _S + 0.2	V _S + 0.6	
V _{CC} and V _{BS} supply undervoltage positive going threshold	6EDL04I06NT 6EDL04I06PT	V _{CCUV+} V _{BSUV+}	11	11.7	12.5	V
	6EDL04N06PT 6EDL04N02PR		8.3	9	9.8	
V _{CC} and V _{BS} supply undervoltage negative going threshold	6EDL04I06NT 6EDL04I06PT	V _{CCUV-} V _{BSUV-}	9.5	9.8	10.8	
	6EDL04N06PT 6EDL04N02PR		7.5	8.1	8.8	

Table 6 Static parameters

Parameter		Symbol	Values			Unit	Test condition	
			Min.	Typ.	Max.			
V _{CC} and V _{BS} supply undervoltage lockout hysteresis	6EDL04I06PT 6EDL04I06PT	V _{CCUVH} V _{BSUVH}	1.2	1.9	-	V		
	6EDL04N06PT 6EDL04N02PR		0.5	0.9	-			
High side leakage current betw. VS and VSS		I _{LVS+}		1	12.5	μA	V _S = 600V	
High side leakage current betw. VS and VSS		I _{LVS+} ¹	-	10	-		T _J =125°C, V _S =600V	
High side leakage current between VSx and VSy (x=1,2,3 and y=1,2,3)		I _{LVS-} ¹	-	10	-		T _J = 125°C V _{Sx} - V _{Sy} = 600V	
Quiescent current V _{BS} supply (VB only)		I _{QBS1}	-	210	400		HO=low	
Quiescent current V _{BS} supply (VB only)		I _{QBS2}	-	210	400		HO=high	
Quiescent current V _{CC} supply (VCC only)	6EDL04I06NT	I _{QCC1}	-	1.1	1.8	mA	V _{LIN} =float. (all) V _{VSx} =50V (only bootstrap types)	
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR		-	0.75	1.5			
Quiescent current V _{CC} supply (VCC only)	6EDL04I06NT	I _{QCC2}	-	1.3	2			V _{LIN} =0, V _{HIN} =3.3 V V _{VSx} =50V
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR			0.75	1.5			V _{LIN} =3.3 V, V _{HIN} =0 V _{VSx} =50V
Quiescent current V _{CC} supply (VCC only)	6EDL04I06NT	I _{QCC3}	-	1.3	2			V _{LIN} =3.3 V, V _{HIN} =0 V _{VSx} =50V
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR			0.75	1.5	V _{LIN} =3.3 V, V _{HIN} =0 V _{VSx} =50V		
Input bias current	6EDL04I06NT	I _{LIN+}	-	70	100	μA	V _{LIN} =3.3 V	
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR		400	700	1100			
Input bias current	6EDL04I06NT	I _{LIN-}	-	110	200	μA	V _{LIN} =0	
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR			0				
Input bias current	6EDL04I06NT	I _{HIN+}	-	70	100	μA	V _{HIN} =3.3 V	
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR		400	700	1100			
Input bias current	6EDL04I06NT	I _{HIN-}	-	110	200	μA	V _{HIN} =0	
	6EDL04I06PT 6EDL04N06PT 6EDL04N02PR			0				
Input bias current (ITRIP=high)		I _{ITRIP+}		45	120	μA	V _{ITRIP} =3.3 V	
Input bias current (EN=high)		I _{EN+}	-	45	120	μA	V _{ENABLE} =3.3 V	
Input bias current RCIN (internal current source)		I _{RCIN}		2.8		μA	V _{RCIN} = 2 V	

¹ Not subject of production test, verified by characterisation

Table 6 Static parameters

Parameter	Symbol	Values			Unit	Test condition
		Min.	Typ.	Max.		
Mean output current for load capacity charging in range from 3 V (20%) to 6 V (40%)	I_{O+}	120	165	-	mA	$C_L=10$ nF
Peak output current turn on (single pulse)	I_{Opk+}^1		240			$R_L = 0 \Omega, t_p < 10 \mu s$
Mean output current for load capacity discharging in range from 12 V (80%) to 9 V (60%)	I_{O-}	250	375	-		$C_L=10$ nF
Peak output current turn off (single pulse)	I_{Opk-}^1		420			$R_L = 0 \Omega, t_p < 10 \mu s$
Bootstrap diode forward voltage between VCC and VB	$V_{F,BSD}$	-	1.0	1.3	V	$I_F=0.5$ mA
Bootstrap diode forward current between VCC and VB	$I_{F,BSD}$	27	51	75	mA	$V_F=4$ V
Bootstrap diode resistance	R_{BSD}	24	40	60		$V_{F1}=4$ V, $V_{F2}=5$ V
RCIN low on resistance of the pull down transistor	$R_{on,RCIN}$	-	40	100		$V_{RCIN}=0.5$ V
FAULT low on resistance of the pull down transistor	$R_{on,FLT}$	-	45	100		$V_{FAULT}=0.5$ V

¹ Not subject of production test, verified by characterisation

4.6 Dynamic parameters

$V_{CC} = V_{BS} = 15\text{ V}$, $V_S = V_{SS} = V_{COM}$ unless otherwise specified. All parameters are valid for $T_a=25\text{ °C}$.

Table 7 Dynamic parameters

Parameter	Symbol	Values			Unit	Test condition		
		Min.	Typ.	Max.				
Turn-on propagation delay	t_{on}	400	530	800	ns	$V_{LIN/HIN} = 0$ or 3.3 V		
Turn-off propagation delay	6EDL04I06NT 6EDL04I06PT	t_{off}	360	490			760	
			6EDL04N06PT 6EDL04N02PR	400			530	800
Turn-on rise time	t_r	-	60	100			ms	$V_{LIN/HIN} = 0$ or 3.3 V $C_L = 1\text{ nF}$
Turn-off fall time	t_f	-	26	45				
Shutdown propagation delay ENABLE	t_{EN}	-	780	1100				
Shutdown propagation delay ITRIP	t_{ITRIP}	400	670	1000				
Input filter time ITRIP	$t_{ITRIPMIN}$	155	230	380				
Propagation delay ITRIP to FAULT	t_{FLT}	-	420	700				
Input filter time at LIN/HIN for turn on and off	t_{FILIN}	120	300	-				
Input filter time EN	t_{FILEN}	300	600	-				
Fault clear time at RCIN after ITRIP-fault, ($C_{RCin}=1\text{ nF}$)	t_{FLTCLR}	1.0	1.9	3.0				
Dead time	DT	150	310	-	ns	$V_{LIN/HIN} = 0$ & 3.3 V external dead time > 500 ns		
Matching delay ON, max(ton)-min(ton), ton are applicable to all 6 driver outputs	MT_{ON}	-	20	100				
Matching delay OFF, max(toff)-min(toff), toff are applicable to all 6 driver outputs	MT_{OFF}	-	40	100				
Output pulse width matching. $PW_{in}-PW_{out}$	6EDL04I06NT 6EDL04I06PT	PM	40	100				
	6EDL04N06PT 6EDL04N02PR		10	100				

5 Timing diagrams

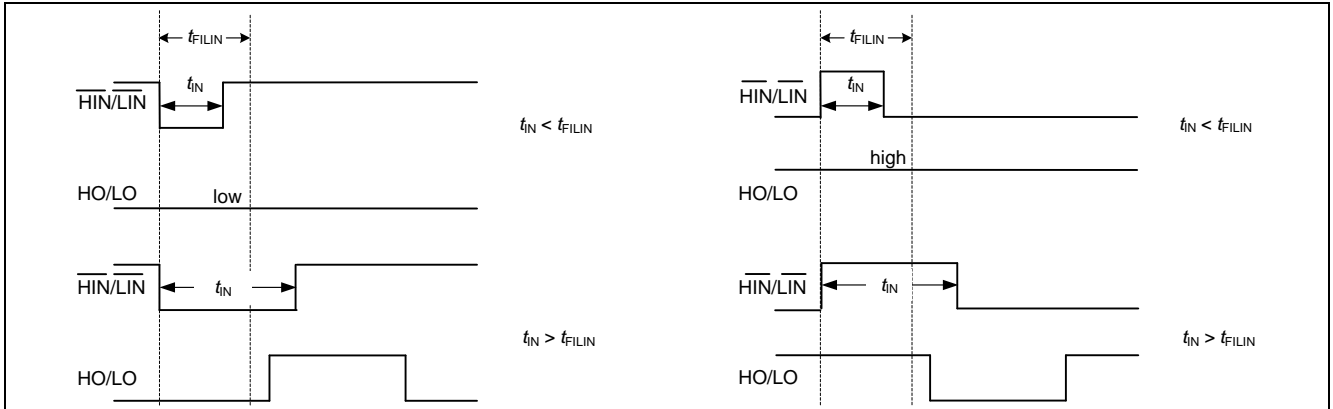


Figure 9 Timing of short pulse suppression (6EDL04I06NT)

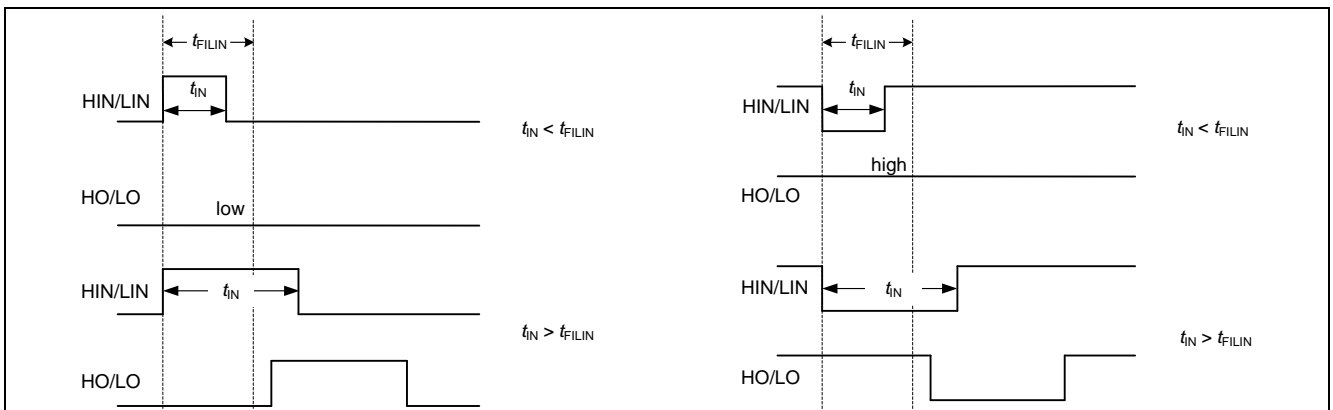


Figure 10 Timing of short pulse suppression (6EDL04I06PT, 6EDL04N06PT, 6EDL04N02PR)

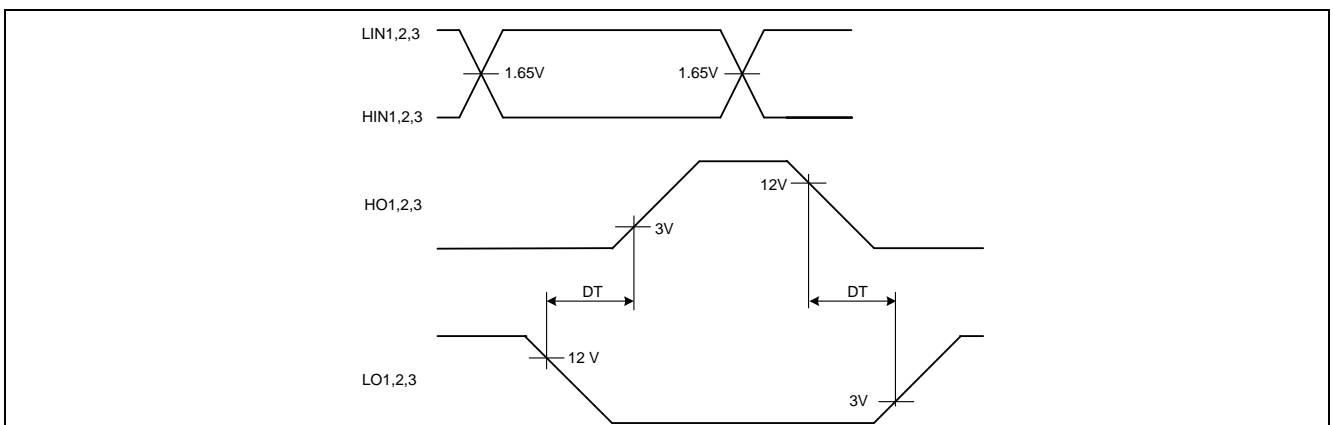


Figure 11 Timing of of internal deadtime (input logic according to Table 1)

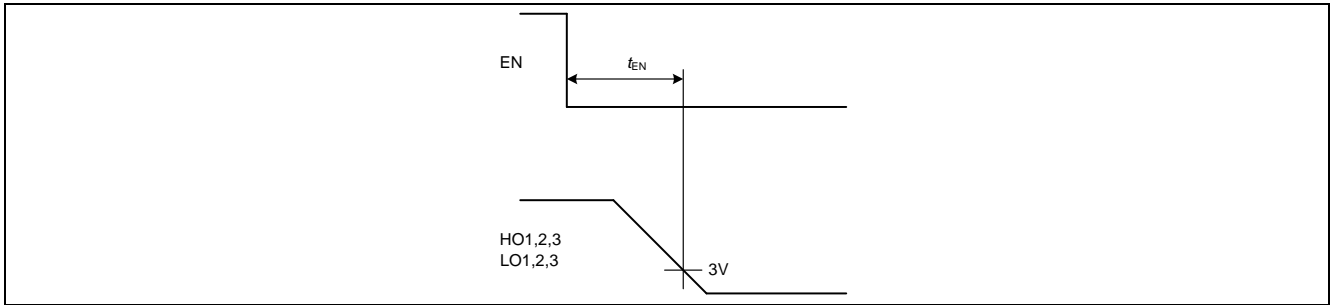


Figure 12 Enable delay time definition

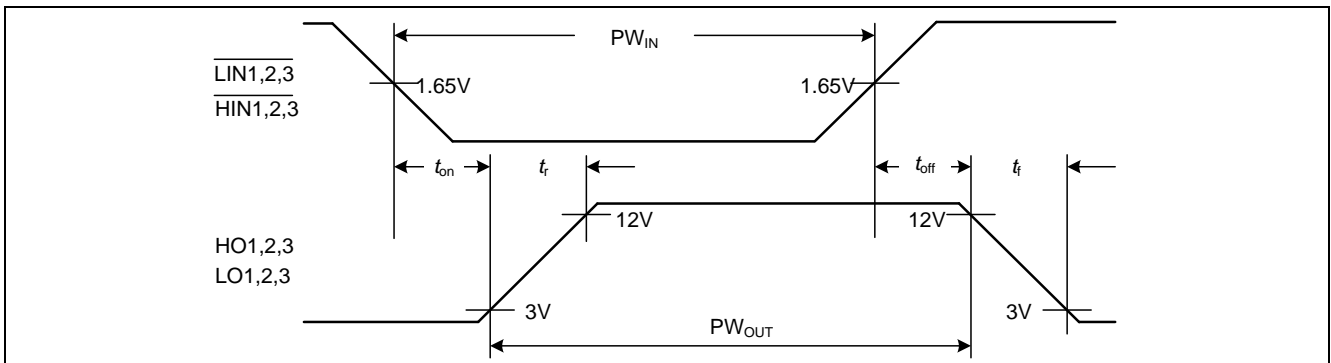


Figure 13 Input to output propagation delay times and switching times definition (6EDL04I06NT)

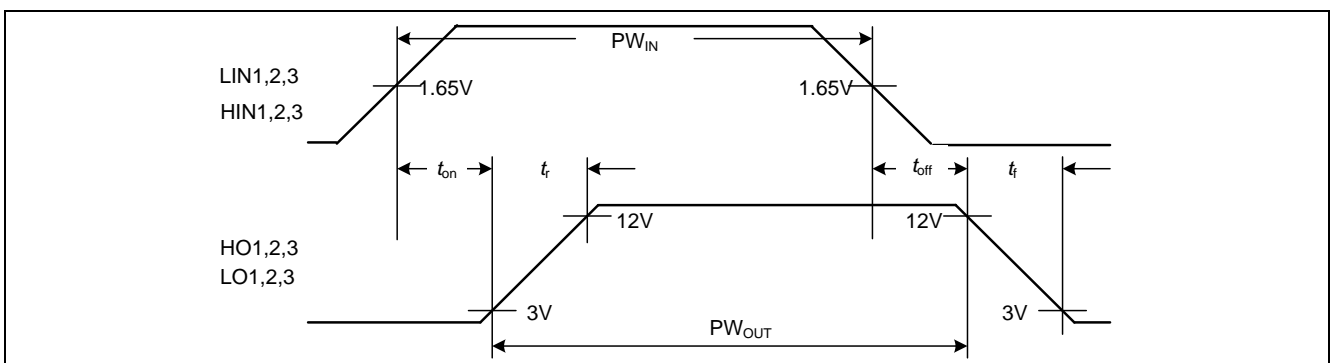


Figure 14 Input to output propagation delay times and switching times definition (6EDL04I06PT, 6EDL04N06PT, 6EDL04N02PR)

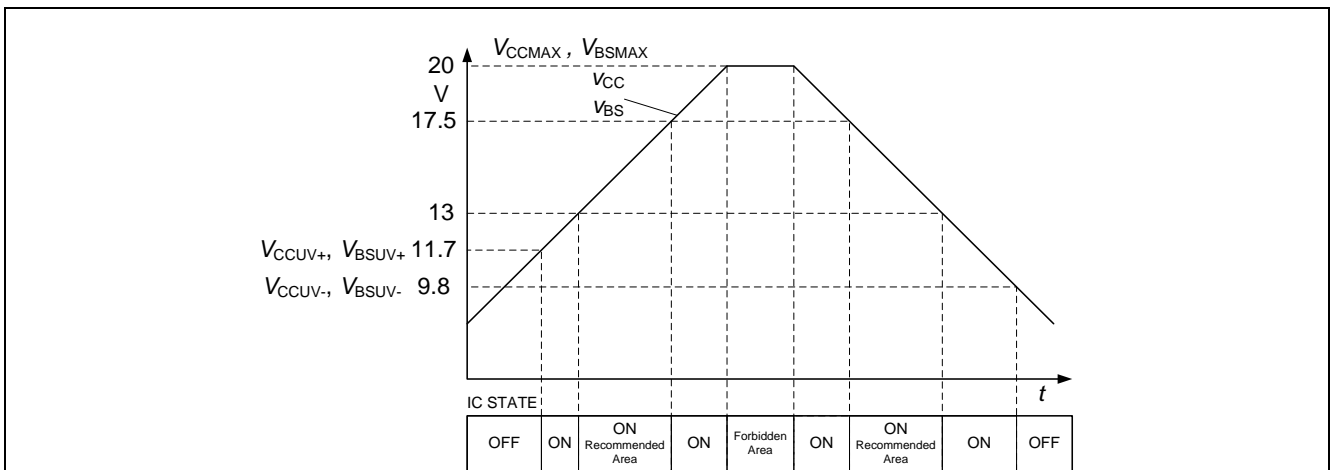


Figure 15 Operating areas (6EDL04I06NT, 6EDL04I06PT)

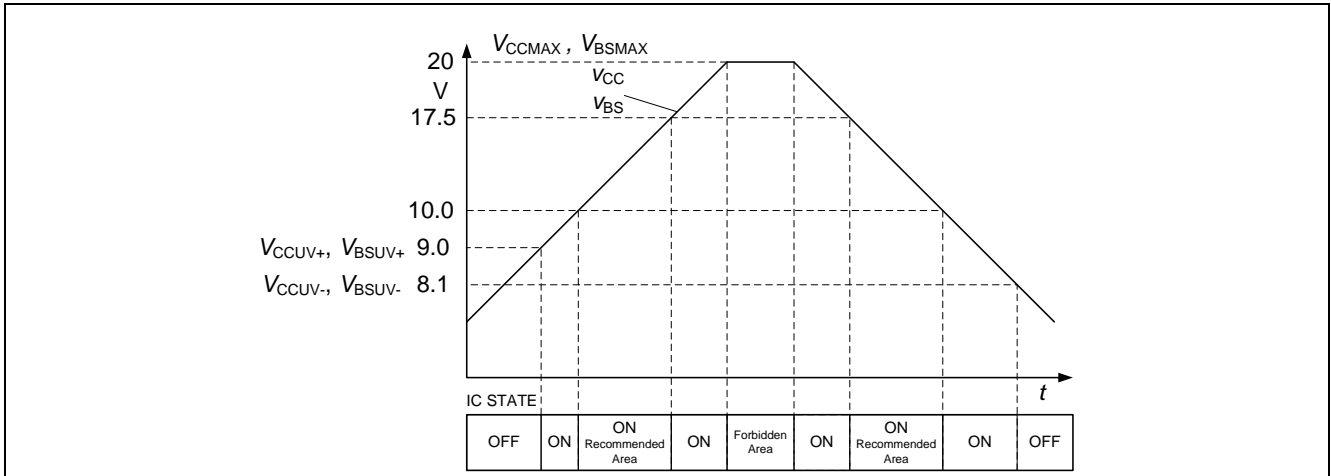


Figure 16 Operating Areas (6EDL04N06PT, 6EDL04N02PR)

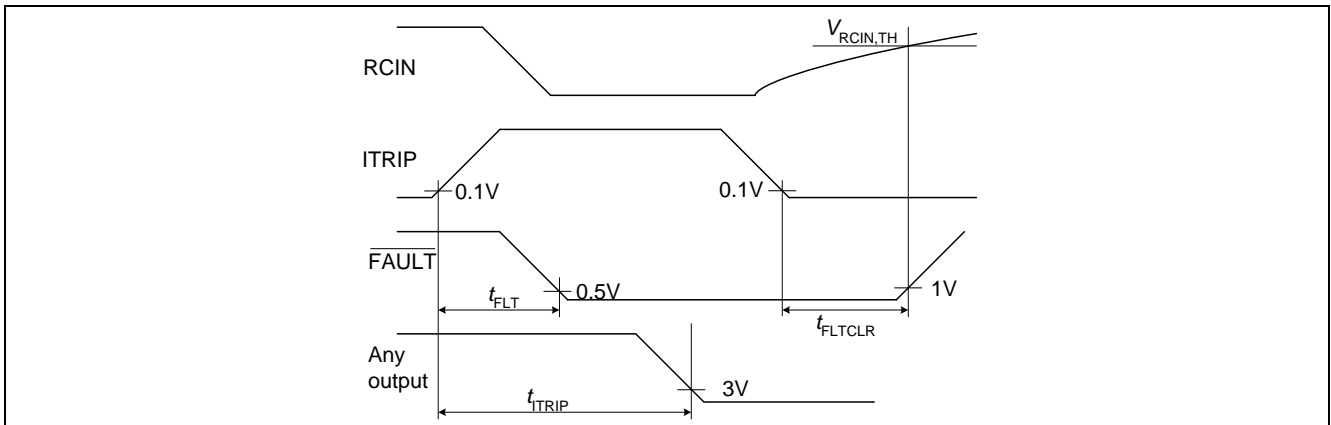


Figure 17 ITRIP-Timing

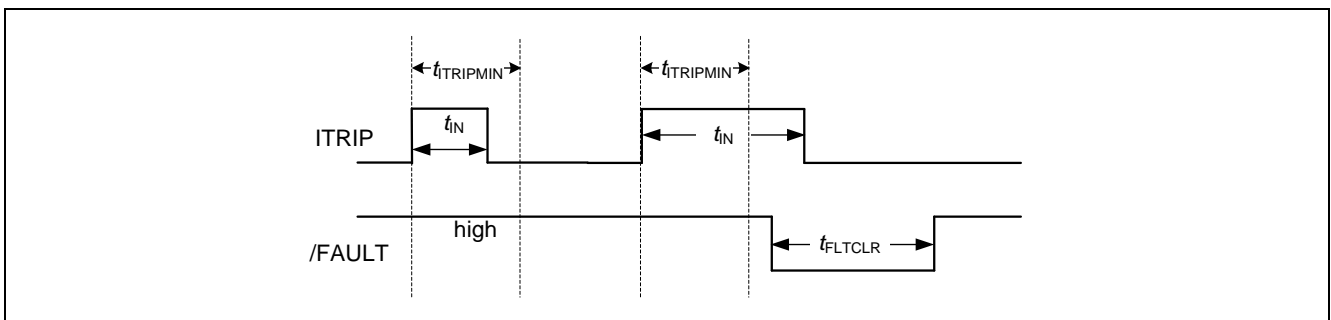


Figure 18 ITRIP Input Timing

6 Package

6.1 PG-DSO-28

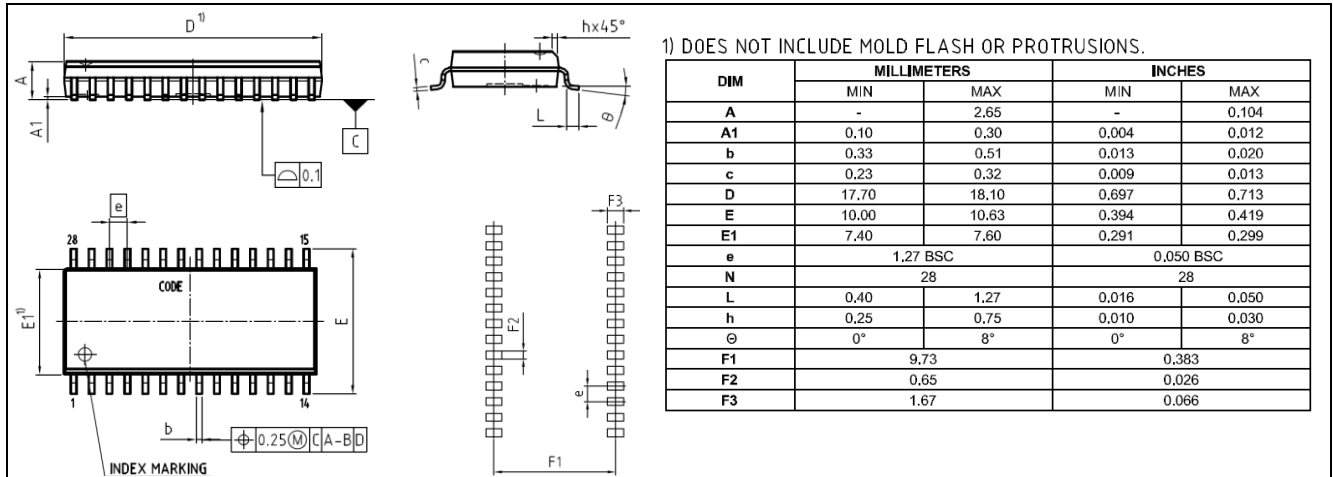


Figure 19 Package drawing

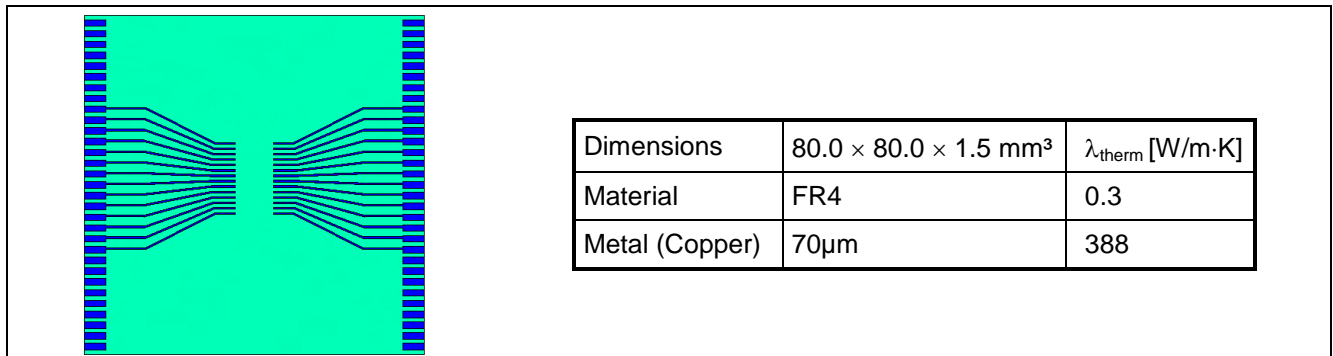


Figure 20 PCB reference layout

6.2 PG-TSSOP-28

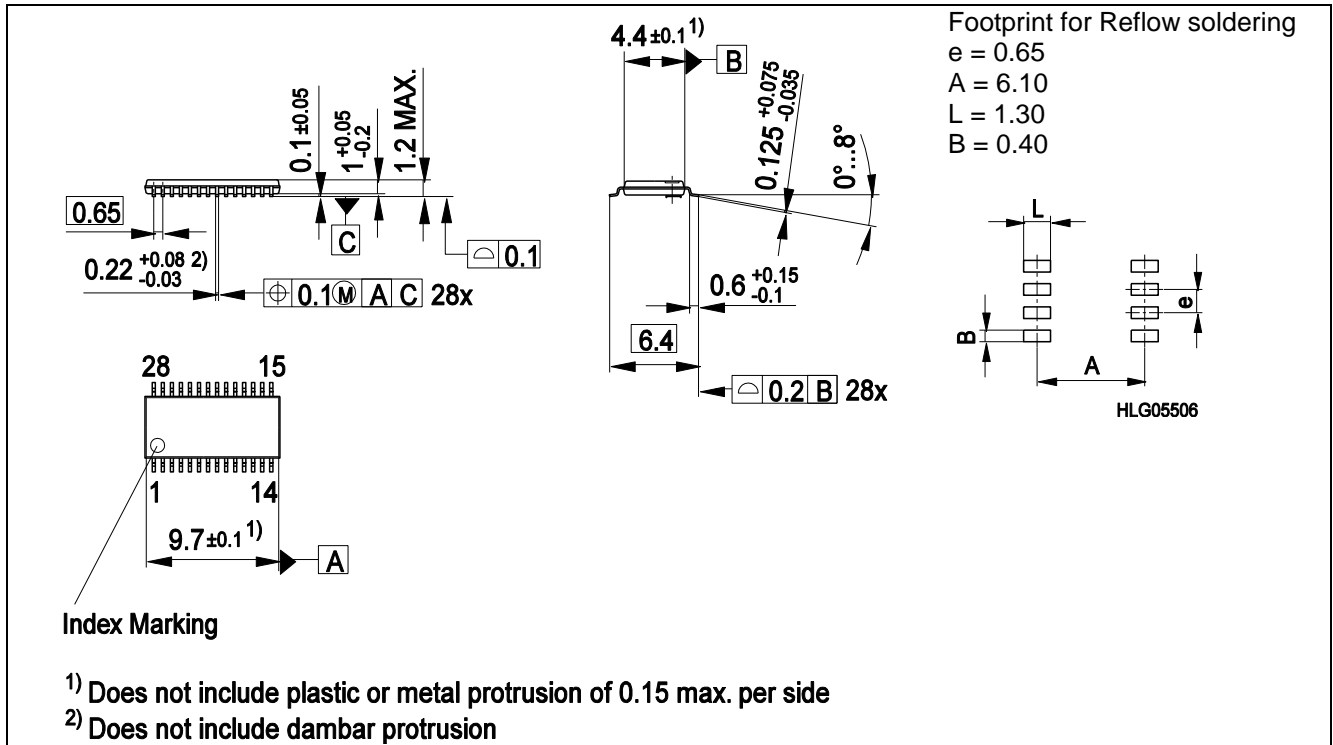


Figure 21 Package drawing

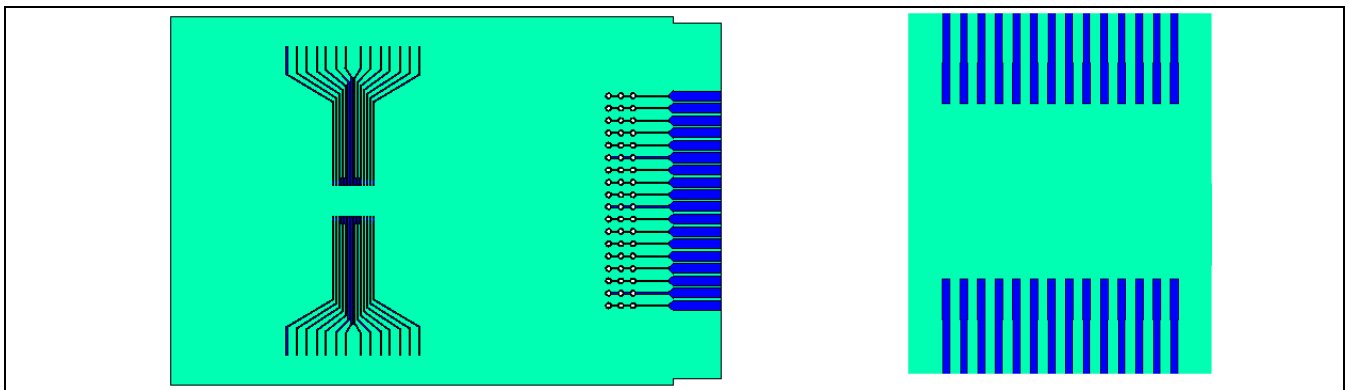


Figure 22 PCB reference layout (according to JEDEC 1s0P)
 left: Reference layout
 right: detail of footprint

Table 8 Data of reference layout

Dimensions	Material	Metal (Copper)
$76.2 \times 114.3 \times 1.5 \text{ mm}^3$	FR4 ($\lambda_{\text{therm}} = 0.3 \text{ W/mK}$)	70 μm ($\lambda_{\text{therm}} = 388 \text{ W/mK}$)

www.infineon.com

Published by Infineon Technologies AG

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Infineon:](#)

[6EDL04N02PRXUMA1](#) [6EDL04I06NTXUMA1](#) [6EDL04I06PTXUMA1](#) [6EDL04N06PTXUMA1](#)